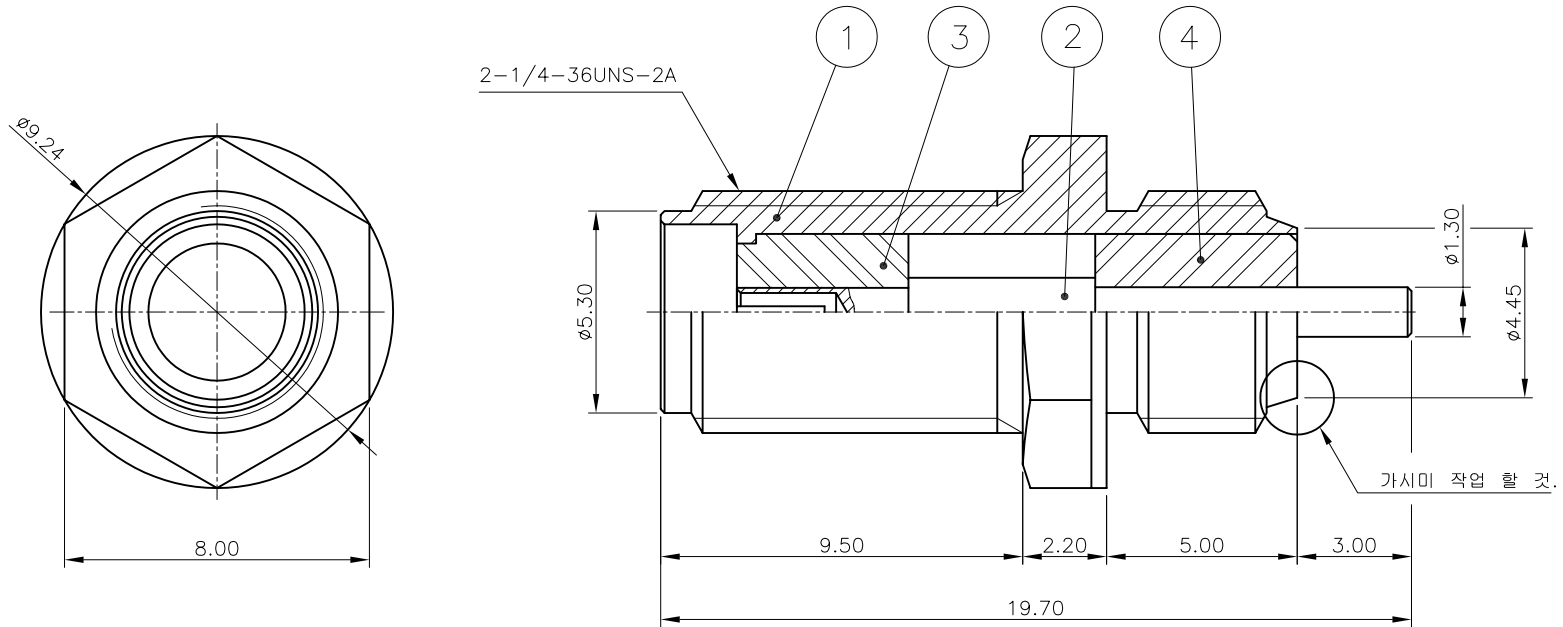


REVISION		
REV	DESCRIPTION	DATE
IR	Initial Registration	2009. 02. 17.
A	조립성 향상[설변200910-0001] (공용TEFLON 공차변경에 따른 코드 변경)	2009. 10. 01.



A	4	INSULATOR	1	TEFLON		DIN00106-N/1 DIN00173-N/1
	3	INSULATOR	1	TEFLON		DIN00207-N/1
	2	CONTACT	1	BeCu	Gold Plate	DCT01912-5/1
	1	BODY	1	MBsBD	Gold Plate	DBD02395-5/1
	NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2009. 10. 01.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY	S.J.YOUN	
MATERIAL	-	CHECKED BY	I.C.KIM	KJ COMTECH CO.,LTD. TITLE SMA50 SOLDER END BJ(F/F)
		DRAWN BY	E.H.KIM	
FINISH	-	SCALE	5/1	A4 DWG NO. CN02338-7/1 REVISION A SHEET 1 of 1
		UNIT	mm	